N-Channel 200V, 22mΩ Typ. Power MOSFET

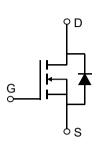
Description

Features

• 200V, 60A

 $R_{DS(ON)}$ Typ = 22m Ω @ V_{GS} = 10V

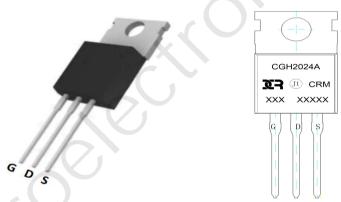
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE(pcs)	Reel (pcs)	Per Carton (pcs)
CRMCGH2024A	CRMCGH2024A	TO-220C-3L	TUBE	50	1000	5000

Absolute Maximum Ratings (@ $T_J = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		200	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	60	А
I _D	Continuous Drain Current	$T_{C} = 100^{\circ}C$ 36	Α	
I _{DM}	Pulsed Drain Current (1)		240	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		605	mJ
P_{D}	Power Dissipation	T _C = 25°C	176	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		0.71	°C/W
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

CRMCGH2024A

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	200	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 200V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5	3.1	3.5	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	22	28.6	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		- /	1293	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$ f = 1MHz	-	1890	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11VII 12	X - \	50	-	pF
Q_g	Total Gate Charge	(45	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 100V, I_{D} = 30A$	U -	15	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 100V, I _D - 30A	-	13	-	nC
Switchin	g Characteristics					
$t_{d(on)}$	Turn-On DelayTime		-	28	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 100V$	-	23	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 30A$, $R_{GEN} = 3\Omega$	-	35	-	ns
\mathbf{t}_{f}	Turn-Off Fall Time		-	24	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
I _S	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	60	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	240	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 204 - 4:1/4 - 40041	-	120	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 30A$, di/dt = 100A/us	-	400	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =30V, V_G =10V, R_G =25ohm, L=10mH, I_{AS} =11A

^{3.} Pulse Test: Pulse Width $\!\!\leqslant\! 300\mu s,$ Duty Cycle $\!\!\leqslant\! 0.5\%.$

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Test Circuit

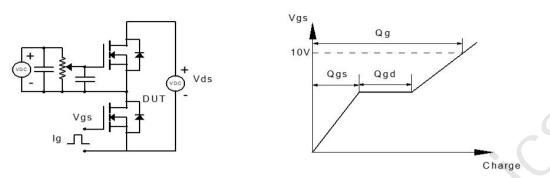


Figure 1: Gate Charge Test Circuit & Waveform

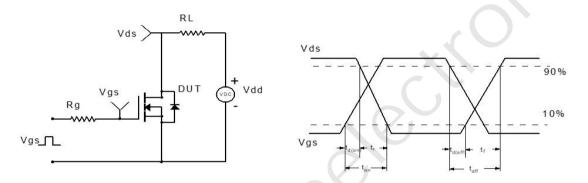


Figure 2: Resistive Switching Test Circuit & Waveform

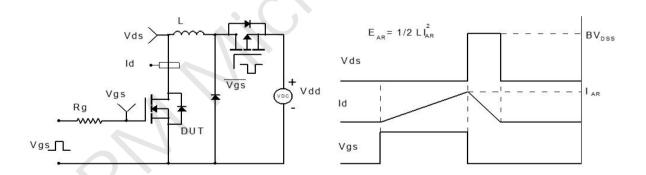


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

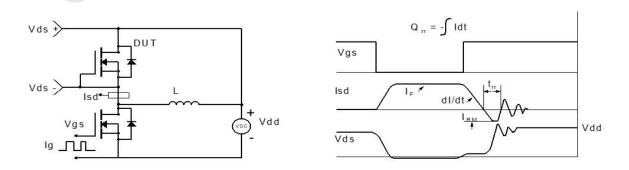
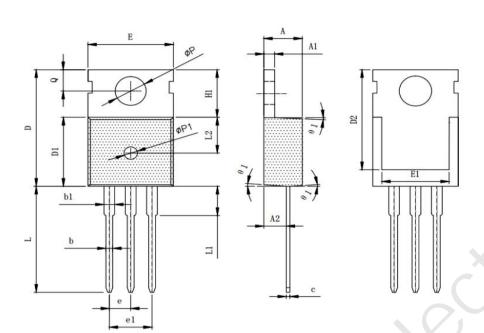


Figure 4: Diode Recovery Test Circuit & Waveform

CRMCGH2024A

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Package Mechanical Data(TO-220C-3L)



CVMDOI	MILLIMETER			
SYMBOL	MIN	NOM	MAX	
A	4. 40	4. 50	4. 60	
A1	1.25	1.30	1. 35	
A2	2.30	2. 40	2. 50	
b	0.70	0.80	0.90	
b1	1. 25	1. 35	1. 45	
С	0. 40	0, 50	0.60	
D	15. 50	15. 80	16. 10	
D1	9. 10	9. 20	9.30	
D2	12. 73	12. 83	12. 93	
Е	9. 70	9. 90	10. 20	
E1	7.60	8.00	8, 40	
e	2. 54 (BSC)			
e1	5. 08 (BSC)			
HI	6, 30	6. 50 6.		
L	12. 75	13. 08	13. 50	
L1			3. 10	
L2	4, 30	4. 60	4. 90	
ΦP	3. 50	3. 60	3. 70	
øP1	1. 40	1. 50	1.60	
a	2.70		2. 90	
9 1	2°	4°	6°	

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